



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-07-03
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EB6R*VA01AAJ	A	ZY1A	2013-07-03
Amount	UoM	Unit type	ST ECOPACK Grade	
54.58	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	5X4.4X0.9	14	gull wing	
Comment	Package: TSSOP 14 BODY 4.4 PITCH 0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EB6R*VA01AAJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	0.694	mg		DIE	Silicon (Si)	7440-21-3		0.679	mg	978386	12441
SILICON DIE					PASSIVATION	Gamma-butyrolactone	96-48-0		0.01	mg	14409	183
SILICON DIE					PASSIVATION	Polyhydroxyamide	55295-98-2		0.005	mg	7205	92
LEADFRAME	Copper & its alloys	21.407	mg		ALLOY	Copper (Cu)	7440-50-8		20.553	mg	960107	376573
LEADFRAME					ALLOY	Iron (Fe)	7439-89-6		0.506	mg	23637	9271
LEADFRAME					ALLOY	Zinc (Zn)	7440-66-6		0.028	mg	1308	513
LEADFRAME					ALLOY	Phosphorus (P)	7723-14-0		0.008	mg	374	147
LEADFRAME					ALLOY	Silver (Ag)	7440-22-4		0.312	mg	14575	5716
DIE ATTACH	Other Organic Materials	2.468	mg		GLUE	Epoxy Resin A	9003-36-5		0.173	mg	70097	3170
DIE ATTACH					GLUE	Epoxy Resin B	68475-94-5		0.099	mg	40113	1814
DIE ATTACH					GLUE	Silver (Ag)	7440-22-4		1.899	mg	769449	34794
DIE ATTACH					GLUE	Lactone	96-48-0		0.099	mg	40113	1814
DIE ATTACH					GLUE	Polyoxypropylenediamine	9046-10-0		0.099	mg	40113	1814
DIE ATTACH					GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Proprietary		0.099	mg	40113	1814
BONDING WIRE	Precious metals	0.29	mg		BONDING WIRE	Gold (Au)	7440-57-5		0.29	mg	1000000	5313
ENCAPSULATION	Other Organic Materials	28.36	mg		MOLDING COMPOUND	Epoxy Resin	Proprietary		2.552	mg	89986	46758
ENCAPSULATION					MOLDING COMPOUND	Silica Fused	60676-86-0		23.823	mg	840021	436487
ENCAPSULATION					MOLDING COMPOUND	Phenol Resin	Proprietary		1.843	mg	64986	33768
ENCAPSULATION					MOLDING COMPOUND	Carbon Black	1333-86-4		0.142	mg	5007	2602
FINISHING	Other inorganic materials	1.36	mg		CONNECTION COATING	Tin (Sn)	7440-31-5		1.36	mg	1000000	24918